



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-10
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KDK7*0339BL6	A	BO2A	2016-06-10
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MDF valid for LM2901HYDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KDK7*0339BL6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.795	mg	supplier	die	Silicon (Si)	7440-21-3		0.782	mg	983648	6015
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	7547	46
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	3774	23
Leadframe	Copper & its alloys	37.266	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	5031	31
				supplier	alloy	Copper (Cu)	7440-50-8		35.999	mg	966001	276915
				supplier	alloy	Iron (Fe)	7439-89-6		0.847	mg	22728	6515
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1369	392
				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1181	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.139	mg	3730	1069
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	134	38
Die attach	Other Organic Materials	0.349	mg	supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	107	31
				supplier	metallization	Silver (Ag)	7440-22-4		0.177	mg	4750	1362
				supplier	glue	Silver (Ag)	7440-22-4		0.294	mg	842407	2262
				supplier	glue	acrylate	Proprietary		0.016	mg	45845	123
				supplier	glue	Methacrylate	Proprietary		0.013	mg	37249	100
Bonding wire	Other inorganic materials	0.114	mg	supplier	glue	acrylate	Proprietary		0.013	mg	37249	100
				SVHC	glue	NMP	872-50-4		0.013	mg	37249	100
encapsulation	Other Organic Materials	90.470	mg	supplier	wire	Copper (Cu)	7440-50-8		0.114	mg	1000000	877
				supplier	mold compound	Silica, vitreous	60676-86-0		78.347	mg	866000	602669
				supplier	mold compound	Epoxy Resin	Proprietary		6.785	mg	74997	52192
				supplier	mold compound	Phenol Resin	Proprietary		4.524	mg	50006	34800
connections coating	Solder	1.006	mg	supplier	mold compound	Carbon black	1333-86-4		0.452	mg	4996	3477
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.362	mg	4001	2785
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.006	mg	1000000	7738